

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar et al. Examiner: Unknown
Serial No.: Unknown Group Art Unit: Unknown
Filed: Herewith Docket: 303.469US3
Title: THERMAL PROCESSING OF METAL ALLOYS FOR AN IMPROVED CMP
PROCESS IN INTEGRATED CIRCUIT FABRICATION

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

When the above-identified patent application is taken up for consideration, please amend the application as follows:

IN THE SPECIFICATION

On page 1, please add the following new paragraph under the title:

A1 --This application is a Continuation of U.S. Application No. 09/038,252, filed on March 10, 1998.--
now US 6,316,356

IN THE CLAIMS

Please cancel claims 1-17 after adding the following new claims.

Sub B27 20. A memory device comprising:
an array of memory cells;
internal circuitry; and
A2 metal contacts and interconnects coupled to the memory cells and internal circuitry,
wherein the metal contacts and interconnects are formed by annealing the memory at a
temperature sufficient to drive alloy dopants into solid solution prior to polishing the memory
device to remove portions of a metal layer and form the metal contacts and interconnects.

C 21. The memory device of claim 20 wherein the memory device is annealed following
polishing of the memory device to increase the conductivity of the metal contacts and
interconnects.